Method for fastening chips with a contact element onto a substrate provided with a functional layer having openings for the chip contact elements

Abstract

This invention relates to a method for tacking of chips (4) onto a substrate (1) at chip positions (1c) which are distributed on a surface (1o) of the substrate (1) with the following steps, especially the following sequence:

- formation or application of a function layer (7) to the substrate (1)
  a) which layer has been uncovered at the chip positions (1c) at least in the region of contacts (2) by structuring or
  b) by uncovering of a function layer (7) which has been uncovered on the surface (1o) at the chip positions (1c) at least in the region of the contacts (2) after formation or application of the function layer (7),
- tacking of chips (4) onto one chip contact side (7o) of the function layer (7) at the chip positions (1c) and contact-making of the contacts (2) via contact elements (3).

Figure 3b